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# DIGITAL TEMPERATURE SENSORS

# **Product Description**

The TSD Series are digital thermopile sensors in a TO5 package. The TSD sensors include an infrared sensor (thermopile) and a sensor signal conditioner.

The TSD sensors can be interfaced to any microcontroller by an I<sup>2</sup>C interface. This microcontroller has to calculate the temperature results based on the ADC values and the calibration parameters



### **Features**

- 0°C ... up to +300°C measurement ranges
- Small size
- Small field of view available
- Up to ±1°C accuracy
- I<sup>2</sup>C Interface
- Low current consumption
- Operating Temperature Range: -10°C ... +85°C

# **Applications**

- Contactless temperature measurement
- Climate control
- Industrial process control
- Household applications

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Digital Thermopile Sensor

# **Absolute Maximum Ratings**

Absolute maximum ratings are limiting values of permitted operation and should never be exceeded under the worst possible conditions either initially or consequently. If exceeded by even the smallest amount, instantaneous catastrophic failure can occur. Even if the device continues to operate satisfactorily, its life may be considerably shortened.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Supply voltage	$V_{DD}$		-0.3		+3.63	V
Storage temperature	T <sub>stor</sub>	dry	-20		+85	°C
Voltage at supply and IO pins	V <sub>DD</sub> V <sub>IO</sub>		-0.5		V <sub>DD</sub> +0.5	V
Current into supply and IO pins	I <sub>IN</sub>		-100		100	mA
ESD rating	ESD	Human Body Model	-2		+2	kV
Humidity	Hum		Non condensing			

# **Operating Conditions**

If not otherwise noted, 3.3V supply voltage is applied.

Parameter	Symbol	Condition		Тур	Max	Unit
Operating supply voltage	$V_{DD}$	stabilized, 100nF	1.68		3.6	V
VDD rise time	t <sub>VDD</sub>				200	μs
Operating temperature	Тор		-20		+85	°C
Resolution	RES				0.1	°C
Supply Current		Active state, average		1050	1500	μΑ
Supply Current	I <sub>VDD</sub>	Sleep state, idle current		20	25	nA
Serial data clock I2C	F <sub>SCL</sub>		10	100	400	kHz
Self-heating	SH	1 sample/s, still air, 60s			+0.2	°C
VDD capacitor	$C_{VDD}$	Place close to the sensor		100		nF

# Thermopile Component

If not otherwise noted, 3.3V supply voltage is applied.

Parameter	Symbol	Condition	Sensor	Min	Тур	Max	Unit
Absorber area	А				0.8 x 0.8		mm
Field of view	FOV	At 50% of maximum signal	TSD305-1C55 TSD305-2C55 TSD305-3C55		88		deg
			TSD305-1SL10		10		deg
Filter transmission range		Long wave pass	TSD305-1C55 TSD305-2C55 TSD305-3C55	>5.5			μm
	inter transmission range		TSD305-1SL10	≥1.1			μm

Digital Thermopile Sensor

Analogue to Digital Converter

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Resolution	ADC <sub>RES</sub>			16		bit
Conversion time	t <sub>CONV</sub>			44.8	59.2	ms
Rise time	t <sub>63</sub>	Including rise time of sensor element			44.8	ms
Resolution internal temperature sensor	ITS <sub>RES</sub>			0.003		K/LSB

Object temperature range

Parameter	Symbol	Sensor	Min	Тур	Max	Unit
Object towns return yours 1)	_	TSD305-1C55 TSD305-3C55	0		+100	°C
Object temperature range 1)	I OBJ	TSD305-2C55 TSD305-1SL10	0		+300	°C

<sup>1)</sup> Other temperatures on request

### **Tolerances**

If not otherwise noted, 3.3V supply voltage is applied.

 $T_{sen}$  = sensor temperature,  $T_{obj}$  = object temperature

Parameter	Symbol	Sensor Temperature	Sensor	Object Temperature	Max	Unit
Acquirect Standard Town 1)	A.C.C	+15°C < T <sub>sen</sub> < +35°C	TSD305-1C55 TSD305-3C55	+40°C < T <sub>obj</sub> < +80°C	14	%FS
Accuracy Standard Temp 1)	ACCs	+15 C < 1 <sub>sen</sub> < +35 C	TSD305-2C55 TSD305-1SL10	+170°C < T <sub>obj</sub> < +190°	±1	70FS
		Complete range	TSD305-1C55	+40°C < T <sub>obj</sub> < +80°C		
Accuracy Extended Temp. 1 2)	ACC <sub>E1</sub>	+15°C < T <sub>sen</sub> < +35°C TSD305-3C55		Complete range	+2	%FS
Accuracy Extended Temp. 1 -		Complete range	TSD305-2C55	TSD305-2C55 +170°C < T <sub>obj</sub> < +190°		
		+15°C < T <sub>sen</sub> < +35°C	TSD305-1SL10	Complete range		
Accuracy Extended Temp. 2 2)	ACC <sub>E3</sub>	Complete range	TSD305-1C55 TSD305-2C55 TSD305-3C55 TSD305-1SL10	Complete range	±3	%FS

Other temperature ranges and accuracies are available on request.

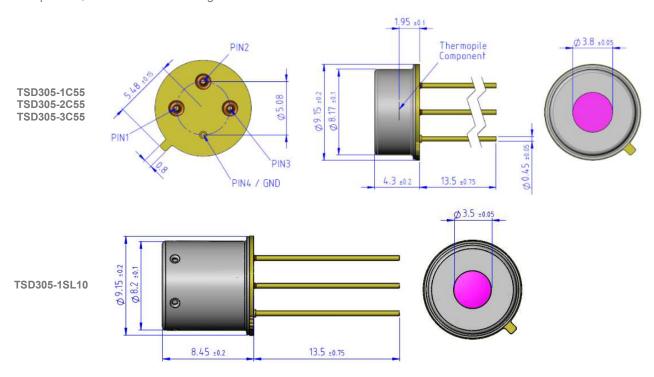
### Power & Reset

Parameter	Symbol	Condition		Тур	Max	Unit
Start-up time	t <sub>STA1</sub>	V <sub>DD</sub> ramp up to interface communication			1	ms
	t <sub>STA2</sub>	V <sub>DD</sub> ramp to first ADC measurement			2.5	ms
Wake up time	t <sub>WUP1</sub>	Sleep to active state interface communication			0.5	ms
	t <sub>WUP2</sub>	Sleep to first ADC measurement			2	ms
Power down time for reset	t <sub>RESET</sub>	VDD <sub>low</sub>	3			μs
VDD low level	VDD <sub>low</sub>		0		0.2	V
VDD rising slope	SR <sub>VDD</sub>		10			V/ms

<sup>1)</sup> Ideal, proved by production 2) Ideal case by design

# **Dimensions**

If not specified, all tolerances according DIN ISO 2768-m.



### Pin Function Table

Pin	Name	Туре	Function
1	SCL	DI	I <sup>2</sup> C Clock
2	SDA	DIO	I <sup>2</sup> C Data
3	$V_{DD}$	Р	Supply Voltage
4	V <sub>SS</sub>	Р	Ground

# I<sup>2</sup>C Interface

An I<sup>2</sup>C communication message starts with a start condition and it is ended by a stop condition.

Most commands consist of two bytes: the address byte and command byte.

# I<sup>2</sup>C ADRESS

The standard I2C address is

Sensor	I2C Address Hex	I2C Address Bin
TSD305-1C55 TSD305-2C55 TSD305-1SL10	0x00	0b000000X
TSD305-3C55	0x1E	0b0011110X

X = 0:  $I^2C$  Write X = 1:  $I^2C$  Read

Digital Thermopile Sensor

# Status Byte

Each return starts with a status byte followed by the requested data word.

Bit	7	6	5	4	3	2	1	0
Meaning			Busy			Memory Error		

Busy: 1 = Sensor is busy. The requested data is not available yet.

Memory Error: 1 = Memory integrity check failed. Memory was changed after factory calibration.

### **COMMANDS**

Note: Each return starts with a status byte followed by the requested data word. Please take care to wait a certain time after write command before read data.

Command	Return	Description	Typical update rate
0x00 0x39	16 bit EEPROM data	Read data from EEPROM address (0x00 0x39) matching the command	
0xAF	24 bit object temperature ADC, 24 bit sensor temperature ADC	Measure object temperature and sensor temperature ADC 16 times and calculates mean value. Store data in output buffer.	45 ms
0xAE	24 bit object temperature ADC, 24 bit sensor temperature ADC	Measure object temperature and sensor temperature ADC 8 times and calculates mean value. Store data in output buffer.	20 ms
0xAD	24 bit object temperature ADC, 24 bit sensor temperature ADC	Measure object temperature and sensor temperature ADC 4 times and calculates mean value. Store data in output buffer.	15 ms
0xAC	24 bit object temperature ADC, 24 bit sensor temperature ADC	Measure object temperature and sensor temperature ADC 2 times and calculates mean value. Store data in output buffer.	10 ms
0xAA	24 bit object temperature ADC, 24 bit sensor temperature ADC	Measure object temperature and sensor temperature ADC 1 times and calculates mean value. Store data in output buffer.	5 ms

Best signal to noise ratio will be achieved using command "0xAF" since this uses the maximum oversampling rate of 16 measurements.

### Read EEPROM

Write Command:



# Read EEPROM Data:

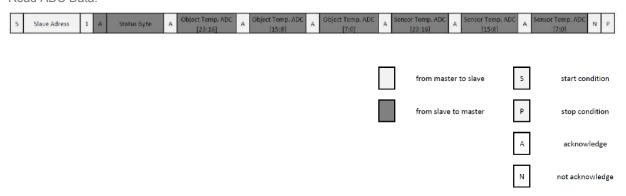


### Perform Measurement and Read ADC Data

Write Command:



### Read ADC Data:



# **EEPROM Content**

Address / hex	Address / dec	Description	Name	Format	Exa	ample
Address / Hex	Address / dec	Description	Name	Tormat	Content	Value
0x00	0	Lot Nr.		UINT16	15001	YY WWW
0x01	1	Serial Number		UINT16	12345	Number
0X02	2	I <sup>2</sup> C Address Valid range: 0x00 0x7F, 0x04 0x07 are reserved	I <sup>2</sup> CAdd	UINT16	0x00	0
0x03 0x19	2 25	Factory Calibration Data				
0x1A	26	Min. Sensor Temp. / °C	T <sub>SenMin</sub>	SINT16	0xFFEC	-20°C
0x1B	27	Max. Sensor Temp. / °C	T <sub>SenMax</sub>	SINT16	0x0055	+85°C
0x1C	28	Min. Object Temp. / °C	$T_{ObjMin}$	SINT16	0x0000	0°C
0x1D	29	Max. Object Temp. / °C	T <sub>ObjMax</sub>	SINT16	0x0064	100°C
0x1E	30	T		IEEE 754 H-Word	0xBB96	0.0040
0x1F	31	Temperature Coefficient	TC	IEEE 754 L-Word	0xBB99	-0.0046
0x20	32	Defense Temperature	_	IEEE 754 H-Word	0x41D7	00.00
0x21	33	Reference Temperature	$T_{REF}$	IEEE 754 L-Word	0x70A4	26.93
0x22	34	Compensation	1.4	IEEE 754 H-Word	0x3A07	5 4045 04
0x23	35	Coefficient k4	k4 <sub>comp</sub>	IEEE 754 L-Word	0x4C8C	5.161E-04
0x24	36	Compensation		IEEE 754 H-Word	0x3F10	
0x25	37	Coefficient k3	k3 <sub>comp</sub>	IEEE 754 L-Word	0x5CEC	5.639E-01
0x26	38	Compensation		IEEE 754 H-Word	0x4367	0.0445.00
0x27	39	Coefficient k2	k2 <sub>comp</sub>	IEEE 754 L-Word	0x0D1F	2.311E+02
0x28	40	Compensation	1.4	IEEE 754 H-Word	0x4724	4.0075.04
0x29	41	Coefficient k1	k1 <sub>comp</sub>	IEEE 754 L-Word	0x5A6F	4.207E+04
0x2A	42	Compensation		IEEE 754 H-Word	0xC9A0	4 0 4 0 5
0x2B	43	Coefficient k0	k0 <sub>comp</sub>	IEEE 754 L-Word	0x254D	-1.312E+06
0x2C	44					
0x2D	45	Not used				
0x2E	46	ADC → T		IEEE 754 H-Word	0x944B	
0x2F	47	Coefficient k4	k4 <sub>Obj</sub>	IEEE 754 L-Word	0xD24F	-1.029E-26
0x30	48	ADC → T		IEEE 754 H-Word	0x2052	
0x31	49	Coefficient k3	k3 <sub>Obj</sub>	IEEE 754 L-Word	0xF1C2	1.787E-19
0x32	50	ADC → T		IEEE 754 H-Word	0xABE5	
0x33	51	Coefficient k2	k2 <sub>Obj</sub>	IEEE 754 L-Word	0x991B	-1.631E-12
0x34	52	ADC → T		IEEE 754 H-Word	0x3797	
0x35	53	Coefficient k1	k1 <sub>Obj</sub>	IEEE 754 L-Word	0x2BBF	1.802E-05
0x36	54	ADC → T		IEEE 754 H-Word	0x41D7	
0x37	55	Coefficient k0	$k0_{Obj}$	IEEE 754 L-Word	0x6DBA	2.693E+01
0x38	56	Factory calibration status – internal usage only		UINT16	TBD	

Change of I<sup>2</sup>C Address
The I<sup>2</sup>C address of each TSD can be modified to use multiple TSDs on one I<sup>2</sup>C bus. The used I<sup>2</sup>C address is configured via an EEPROM address. Power needs to be cycled to active an updated I<sup>2</sup>C address.

Command	Return	Description
0x00 0x39	16 bit EEPROM data	Read data from EEPROM address (0x00 0x39) matching the command
0x40 0x79		Write data from EEPROM address (0x00 0x39).
0x90	***	Calculate and write memory checksum (CRC).  If the CRC is valid, then the "Memory Error" status bit is set to 0.

The commands to read and write the EEPROM are shown below. After changing the I<sup>2</sup>C address, the checksum needs to be recalculated to reset the Memory Error bit.

### **Number Format**

### UINT16

Description: Unsigned integer

Bits 16

0 / 0x0000 / 0b0000 0000 0000 0000 Min (dec/hec/bin) Max (dec/hec/bin) 65,535 / 0xFFFF / 0b1111 1111 1111 1111

### SINT16

Description: Signed integer

Bits 16

Min (dec/hec/bin) -32,768 / 0x8000 / 0b1000 0000 0000 0000 32,767 / 0x7FFF / 0b0111 1111 1111 1111 Max (dec/hec/bin)

### FLOAT IEEE 754

Description: Float Bits 32

Min (dec/hec/bin) Max (dec/hec/bin) 

Example: H-Word 0x3DCC L-Word 0xCCCD

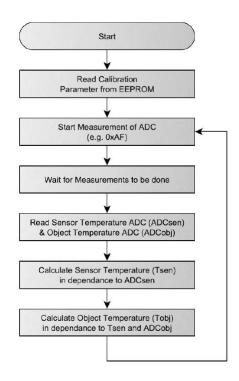
→ 0b0011 1101 1100 1100 1100 1100 1101

### FLOAT IEEE 754 Conversions

The two integer words can easily be converted to a floating-point number by using a union consisting of an integer array and a float.

```
void main(void)
  union
         unsigned int iValue[2]; // 16bit unsigned integer
                                    // float IEEE 754
         float fValue;
  } MyUnion;
  while(1)
         MyUnion.iValue[1] = 0x3dcc;
         MyUnion.iValue[0] = 0xcccd;
         //MyUnion.fValue = 0.1;
```

# **Temperature Calculation**



# Sensor Temperature

The sensor temperature T<sub>Sen</sub> is calculated from the corresponding 24 bit ADC value ADC<sub>sen</sub>.

Name	Description	Format	Range	
			Min	Max
ADC <sub>sen</sub>	ADC Sensor Temperature	INT24	0	16,777,216

ADC<sub>sen</sub> is scaled to cover the complete sensor temperature range from T<sub>SenMin</sub> to T<sub>SenMax</sub>.

Adress / hex	Adress / dec	Description	Name	Format	Exar	mple
					Value	Max
0x1A	26	Min. Sensor Temp. / °C	T <sub>SenMin</sub>	SINT16	0xFFEC	-20°C
0x1B	27	Max. Sensor Temp. / °C	T <sub>SenMax</sub>	SINT16	0x0055	+85°C

Formula:

$$T_{sen}$$
 = ADC<sub>sen</sub> /  $2^{24} \times (T_{SenMax} - T_{SenMin}) + T_{SenMin}$ 

Example:

$$ADC_{sen} = 6,364,157$$

$$T_{sen} = 6.364,157 / 224 \times [+85^{\circ}C - (-20^{\circ}C)] + (-20^{\circ}C) = \underline{19.83^{\circ}C}$$

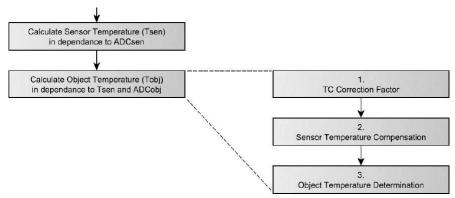
# **Object Temperature**

The object temperature T<sub>obj</sub> is calculated in dependence of the sensor temperature T<sub>sen</sub> and ADC<sub>Obj</sub>.

ADC<sub>obj</sub> is shifted by 2<sup>23</sup> in order to provide unsigned integer values for positive and negative measurement values.

Name	Description	Format	Range	
	·		Min	Max
ADC <sub>obj</sub>	ADC Object Temperature Shifted by 2 <sup>23</sup> (0 is represented by 8,388,608)	INT24	0	16,777,216

The process consists of three successive steps.



### TC Correction Factor

Adress / hex	ress / hex Adress / dec Description Name	Description	Name	Format	Example	
7			Content	Value		
0x1E	30	Temperature Coefficient	TC	IEEE 754 H-Word	0xBB96	0.0046
0x1F	31		TC	IEEE 754 L-Word	0xBB99	-0.0046
0x20	32	D.C. T.	_	IEEE 754 H-Word	0x41D7	+26.93
0x21	33	Reference Temperature	T <sub>REF</sub>	IEEE 754 L-Word	0x70A4	+∠0.93

$$T_{sen} = +19.83^{\circ}C$$

$$T_{ref} = +26.93^{\circ}C$$

TCF = 
$$1 + [(T_{sen} - T_{ref}) \times TC]$$
 TCF =  $1 + [(19.83 - 26.93) \times -0.0046]$  =  $1.0327$ 

# Temperature Compensation

Adress / hex	Adress / dec	Description	Name	Format	Example	
					Content	Value
0x22	34	Compensation	k4	IEEE 754 H-Word	0x3A07	5.161E-04
0x23	35	Coefficient k4	k4 <sub>comp</sub>	IEEE 754 L-Word	0x4C8C	5.101E-04
0x24	36	Compensation Coefficient k3	k2	IEEE 754 H-Word	0x3F10	5.639E-01
0x25	37		k3 <sub>comp</sub>	IEEE 754 L-Word	0x5CEC	5.039⊑-01
0x26	38	Compensation Coefficient k2	k2 <sub>comp</sub>	IEEE 754 H-Word	0x4367	2.311E+02
0x27	39		K∠comp	IEEE 754 L-Word	0x0D1F	2.311E+02
0x28	40	Compensation	k1 <sub>comp</sub>	IEEE 754 H-Word	0x4724	4.207E+04
0x29	41	Coefficient k1	K I comp	IEEE 754 L-Word	0x5A6F	4.207 = +04
0x2A		Compensation	k0	IEEE 754 H-Word	0xC9A0	-1.312E+06
0x2B		Coefficient k0	k0 <sub>comp</sub>	IEEE 754 L-Word	0x254D	-1.312E+00

Formula:		Example:	
		T <sub>sen</sub> =	+19.83°C
		$k4_{comp} \dots k0_{comp}$	See table above
O#224 -	T 4	Office to the	5 404 404 40 004
Offset =	$k4_{comp} \times Tsen^4$ + $k3_{comp} \times Tsen^3$ + $k2_{comp} \times Tsen^2$ + $k1_{comp} \times Tsen$ + $k0_{comp}$	Offset =	$= 5.161 \cdot 10^{-4} \times 19.83^{4}$ $+ 5.639 \cdot 10^{-1} \times 19.83^{3}$ $+ 2.311 \cdot 10^{2} \times 19.83^{2}$ $+ 4.207 \cdot 10^{4} \times 19.83$ $+ -1.312 \cdot 10^{6}$
			= -382,399
Offset <sub>TC</sub> =	Offset × TCF	Offset <sub>TC</sub> =	= -382,399 × 1.0327
			= -394,904

# Object Temperature Determination

Adress / hex	Adress / dec	Adress / dec Description	Name	Format	Example		
					Content	Value	
0x2E	46	ADC → T	k4	IEEE 754 H-Word	0x944B	-1.029E-26	
0x2F	47	Coefficient k4	k4 <sub>Obj</sub>	IEEE 754 L-Word	0xD24F	-1.029E-20	
0x30	48	ADC → T Coefficient k3	k2	IEEE 754 H-Word	0x2052	1.787E-19	
0x31	49		k3 <sub>Obj</sub>	IEEE 754 L-Word	0xF1C2	1.707E-19	
0x32	50	ADC → T	$\Delta$ DC $\rightarrow$ T	k2	IEEE 754 H-Word	0xABE5	-1.631E-12
0x33	51	Coefficient k2	k2 <sub>Obj</sub>	IEEE 754 L-Word	0x991B	-1.031E-12	
0x34	52	ADC → T	k1 <sub>Obi</sub>	IEEE 754 H-Word	0x3797	1.802E-05	
0x35	53	Coefficient k1	K I Obj	IEEE 754 L-Word	0x2BBF	1.002E-03	
0x36	54	ADC → T	k0	IEEE 754 H-Word	0x41D7	2.693E+01	
0x37	55	Coefficient k0	k0 <sub>Obj</sub>	IEEE 754 L-Word	0x6DBA	2.093E+01	

Formula:		Example:	
		$ADC_{Obj} = k4_{Obj} \dots k0_{Obj}$	10,738,758 See table above
ADC <sub>comp</sub> =	Offset <sub>TC</sub> + $(ADC_{Obj} - 2^{23})^1$	ADC <sub>Comp</sub> =	= -394,904 + 10,738,758 - 8,388,608 = 1,955,246
ADC <sub>CompTC</sub> =	ADC <sub>Comp</sub> / TCF	ADC <sub>CompTC</sub> =	= 1,955,246 / 1.0327 = 1,893,334
T <sub>Obj</sub> =	$k4_{Obj} \times ADC_{CompTC}^4$ + $k3_{Obj} \times ADC_{CompTC}^3$ + $k2_{Obj} \times ADC_{CompTC}^2$ + $k1_{Obj} \times ADC_{CompTC}$ + $k0_{Obj}$	T <sub>Obj</sub> =	= $-1.029 \cdot 10^{-26} \times 1,893,334^4$ + $1.787 \cdot 10^{-19} \times 1,893,334^3$ + $-1.631 \cdot 10^{-12} \times 1,893,334^2$ + $1.802 \cdot 10^{-5} \times 1,893,334$ + $2.693 \cdot 10$
			= <u>56.28°C</u>

 $<sup>^1</sup>$  Valid if emissivity is 1 (100%). Otherwise the formula in brackets must be replaced by (ADCobj -  $2^{23})$  /  $\epsilon$ . See chapter "Emissivity" on page 13 for details.

### Example Code

This example code is meant to illustrate the basic procedure to determinate the measured sensor and object temperatures with respect to TSD digital thermopile sensors. This code needs to be modified with respect to the

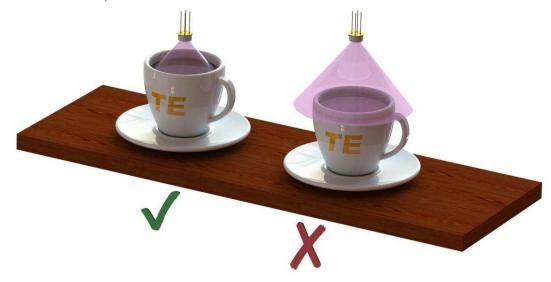
```
// File: TSD_Temperature_Determination_Example.c //
// Date: 01.\overline{1}1.2016 //
// Description: This example code is meant to illustrate the basical procedure //
// to determinat the measured sensor and object temperatures with //
// respect to TSD digital thermopile sensors. //
// This code is not meant to work or to be compiled. //
                                                    void TSD Determinate Temperature (void)
       signed int siMinObjTemp, siMaxObjTemp, siMinSenTemp, siMaxSenTemp;
       float fTC, fTref, fK4com, fK3com, fK2com, fK1com, fK0com, fK4obj, fK3obj,
       fK2obj, fK1obj, fK0obj;
       float fTsen, fTobj;
       float fTCF, fOffset, fADCcomp;
       signed long slADC Object, slADC Sensor;
       // Read Temperature Range Minimum & Maximum
       siMinSenTemp = (signed int)Read EE UInt(26);
       siMaxSenTemp = (signed int)Read EE UInt(27);
       siMinObjTemp = (signed int)Read_EE_UInt(28);
       siMaxObjTemp = (signed int)Read EE UInt(29);
       // Read all necessary coefficients from the memory, float tye
       fTref = Read EE Float(32);
       fTC = Read \to Float(30);
       fTref = Read EE Float (32);
       fK4com = Read EE Float(34);
       fK3com = Read EE Float(36);
       fK2com = Read_EE_Float(38);
fK1com = Read_EE_Float(40);
       fK0com = Read EE Float (42);
       fK4obj = Read_EE_Float(46);
       fK3obj = Read EE Float(48);
       fK2obj = Read EE Float(50);
       fKlobj = Read EE Float(52);
       fK0obj = Read EE Float (54);
       // Read ADC Values for Object Temp. & Sensor Temp.
       Read ADC Values(&slADC_Object, &slADC_Sensor);
       // Calculate Sensor Temp. (slADC_Sensor, Minimum & Maximum Sensor Temp.), Page 8
       fTsen = (float)slADC Sensor / 16777216.0 * (siMaxSenTemp - siMinSenTemp) + siMinSenTemp;
       // Calculate TC Correction Factor (Temp. Coefficient & Reference Temp.), Page 9fTCF = 1.0
       + ((fTsen - fTref) * fTC);
       // Calculate Offset Value, Page 10
       fOffset = fOffset + fK4com * fTsen * fTsen * fTsen * fTsen;
       fOffset = fOffset + fK3com * fTsen * fTsen * fTsen;
       fOffset = fOffset + fK2com * fTsen * fTsen;
       fOffset = fOffset + fK1com * fTsen;
       fOffset = fOffset + fK0com;
       fOffset = fOffset * fTCF;
       // Align ADC Value for Object Temperature, Page 11
       slADC Object = slADC Object - 8388608;
       // Calculate Object Temperature, Page 11
       fADCcomp = (float)slADC Object + fOffset;
       fADCcomp = fADCcomp / fTCF;
       fTobj = fTobj + fK4obj * fADCcomp * fADCcomp * fADCcomp;
       fTobj = fTobj + fK3obj * fADCcomp * fADCcomp;
       fTobj = fTobj + fK2obj * fADCcomp * fADCcomp;
       fTobj = fTobj + fKlobj * fADCcomp;
       fTobj = fTobj + fKOobj;
       // Resulting Sensor Temperature = fTsen
       // Resulting Object Temperature = fTobj
```

}

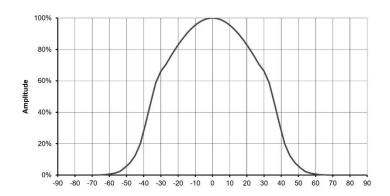
# **Application notes**

### field of view

The thermopile's field of view must be directed to the object surface of interest. The distance to the surface or the surface diameter must be adjusted to ensure that the complete sensors field of view is covered by the object, see example on the left in the picture below.

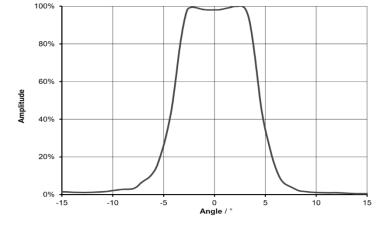


TSD305-1C55 TSD305-2C55



Distance / mm	Min. Diameter / mm
10	24
20	43
30	62
40	82
50	101
100	198
200	391
300	584
400	777
500	970





Distance / mm	Min. Diameter / mm
10	6
20	8
30	10
40	11
50	13
100	22
200	39
300	57
400	74
500	92

### **Direct Sunlight**

Sun light radiation which is transmitted through a glass window may influence the measurement accuracy. To avoid this, the thermopile sensor is equipped with a long wavelength filter. Due to not ideal filter characteristics a small portion of radiation will be added to the radiation of the object. In case of direct sunlight exposure this error can be up to +0.2°C.

### Touching the Sensors Cap

User should avoid touching the sensors cap. There will still be a measurement deviation after changing the sensors temperature rapidly.

### **Emissivity**

Every object is transmitting infrared energy in dependence to its temperature. The emissivity is the ratio of the radiated power by an object to the radiation of an ideal black body. Common materials like liquids, clothes, human skin, foods have emissivity factors >0.90 and therefore they can be measured very accurately without adopting the sensors specification.

To compensate the measurement for an object with significant low emissivity, ADCobi needs to be adjusted.

Name	Description	Format	Ra	nge
	23331,		Min	Max
ADC <sub>obj</sub>	ADC Object Temperature Shifted by 2 <sup>23</sup> (0 is represented by 8,388,608)	INT24	0	16,777,216
ε	Emissivity	100%	0	1

### Formula:

# Example:

= 3

ADC<sub>Obj</sub> = 10,738,758 0.9 (90%)

(ADC<sub>Obj</sub> - 2<sup>23</sup>) / ε  $ADC_{Corr} =$ 

ADC <sub>Corr</sub> =	= 2,611,278
-----------------------	-------------

Material	Emissivity		
Aluminum			
Polished	0.10 - 0.05		
Oxidized	0.10 - 0.40		
Rough	0.10 - 0.30		
Anodized	0.60 - 0.95		
Asphalt	0.90 - 1.00		
Brass			
Polished	0.05		
Oxidized	0.50 - 0.60		
Burnished	0.30		
Ceramic	0.90 - 0.95		
Copper			
Polished	0.10		
Oxidized	0.20 - 0.80		
Foods	0.85 - 1.00		
Gold	0.05		
Glass			
Plate	0.90 - 0.95		
Fused quartz	0.75		

Material	Emissivity		
Human Skin	0.99		
Iron			
Polished	0.20		
Oxidized	0.50 - 0.95		
Rusted	0.50 - 0.70		
Paint			
Aluminum paint	0.50		
Bronze paint	0.80		
On metal	0.60 - 0.90		
On plastic, wood	0.80 - 0.95		
Paper	0.85 - 1.00		
Plastic	0.95 - 1.00		
Stainless Steel			
Polished	0.10 - 0.15		
Oxidized	0.45 - 0.95		
Water			
Liquid	0.90 - 0.95		
Ice	0.95 - 1.00		
Snow	0.80 - 1.00		

Digital Thermopile Sensor

# **Evaluation Kit**

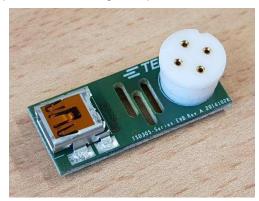
### General description

For easy usage and first trials an evaluation kit is available. It consists of an evaluation board and the "DTS-Viewer"-Software. The eval-board provides an USB to I<sup>2</sup>C interface and can be used on Windows PCs and Android Smartphones with an OTG capable USB port. That means that for example USB flash drives can be connected by an OTG cable to the phone.

The "DTS-Viewer"-Software enables easy measurements and datalogging. This software is available for Windows and Android and supports a wide range of digital temperature sensors provided by TE.

### Evaluation Board Hardware description

The following pictures are showing the top and the bottom side of the eval board PCBA.





It is equipped with the Microchip<sup>™</sup> MPC2221 USB to I<sup>2</sup>C transceiver, a voltage regulator and some passive components. A status LED (red circle) on the bottom of the PCBA indicates power supply and data transmission.

The TSD must be plugged into the white TO socket; the indicator flag of the TSD has to be matched with notch at the socket. The connection to the PC has to be done by a USB cable with Mini-USB-B-plug on the module's side. For connecting to a smartphone an OTG cable is required. This type of cable is used to connect a slave USB device to the USB connector of the smartphone.

### **LED Function Table**

On state	Function
On	Power on
Flashing	Access / data transmission

### DTS-Viewer description (PC version V1.X)

### Overview

The software read out suitable temperature sensors that communicate with an MCP2221 via USB.

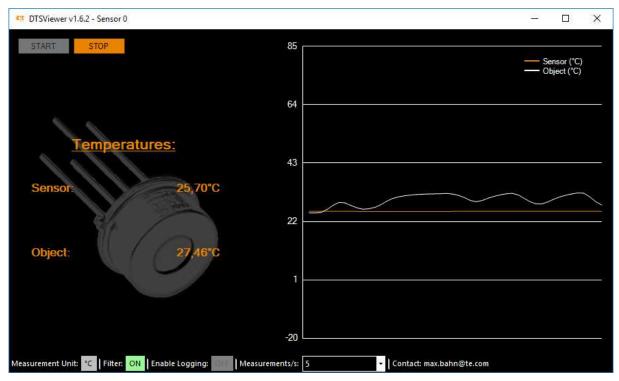
The software can display the temperatures measured by the respective sensor and at the same time display the time course of the last 50 measured values in a graph.

In addition, the measured temperatures can be recorded in a text file via the logging function.

During the measurement it is possible to put a filter over the measured values and to vary the measuring speed in given intervals.

To use the software no special installation process is required. Just start the executable file on the USB flash drive that is provided with the evaluation kit.

The following picture shows the main window that appears after starting the executable file.



### Measurement

First, the evaluation board equipped with a TSD must be connected to the PC.

By pressing the START-button the measurement of both temperatures, sensor package and object temperature is started.

Pressing the STOP-button stops the measurement. Disconnecting the sensor board from the PC has the same effect.

Please note that the DTSViewer V1.X only uses the command "0xAF" with 16 times oversampling. To perform faster measurements the Beta-version of DTSViewer V2.X must be used. See Chapter "Changes in DTSViewer V2.X beta" for details.

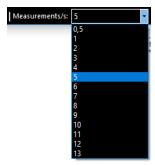
# Switching the temperature Unit

The temperature unit can be changed only when the measurement is running. This is done by clicking on the "Measurement Unit"-Symbol on the lower left area. °C and °F can be selected.

### Measurement Speed

In the drop-down menu "Measurements/s" the measurement speed can be selected, both before and during a running measurement.

You can select from a predefined selection of measurement speeds. The minimum measurement interval is limited by the internal measurement speed of the sensor.



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### Filter

The "Filter" button enables or disables a filter to smooth the measured values. It can be pressed before or during measurement.

The filter used is a very simple implementation of a moving average filter, which is only intended to provide smoothing for unstable measured values. In this implementation the filter considers the last 5 measured values.

Note: If the measured values must be as accurate as possible or if a fast reaction time is required, the filter should be switched off.

### Logging

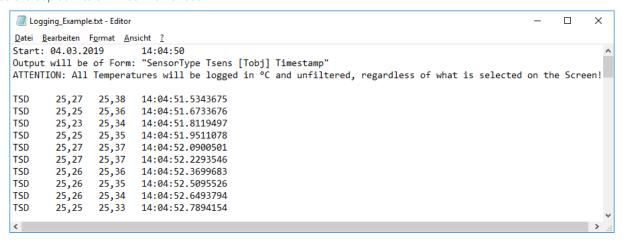
The software can record the measurement data in a text file. The "Enable Logging" button toggles between recording on and off.

If the logging is set to "ON" the user is prompted to select or create a text file which is then used to save the measurement data each time he starts the measurement.

The text file begins with the time and date information and a description of the format used. Then follows the listing of the measured values, together with sensor type and an individual time stamp.

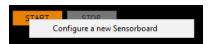
It should be noted that the measured values are always stored in °C and unfiltered, regardless of what the user has previously set in the program. Only the measuring speed has an influence on the stored data.

Note: The measurement data are stored as tabulator delimited values, so each value is written into a new cell if the measured values are copied into an Excel worksheet.



### Configuring a new Sensorboard – internal usage only

To use this function, the user must right-click on the "START" button and then click on the button that appears.



This function is for internal usage only and could lead to malfunction of the evaluation board. If the user activates the function by accident he should leave everything as it is and skip it.

# Changes in DTSViewer V2.X beta

### Overview

The following changes taken place in the DTSViewer V2.X:

- Main screen with slightly different menu bar at the bottom
- Measurement speed adjustable by slider. Limitation of 20 measurements per second can be overridden to achieve faster measurement with lower oversampling.
- New advanced menu to
  - Configure TSD oversampling rate "TSD Speed" by using different commands will be reset to 16 measurements after program restart
  - Configure TSD I<sup>2</sup>C address and set the software to different I<sup>2</sup>C address than 0x00.
  - Configure the eval boards for different TE digital sensors internal usage only.

Currently, there is no possibility to measure the temperatures in °F. This will maybe back in the official released version.

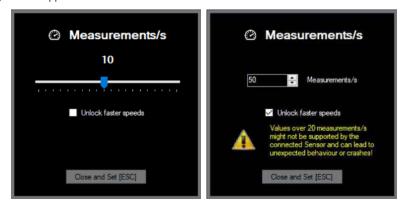
### Main Screen

The main screen of DTSViewer V2.X looks like follows



### Measurement speed

The following pictures show the new design of the measurement/s menu. The left picture shows the slider. When enabling faster speeds by clicking the checkbox the right menu appears.



Since this is only the request frequency of the display and logging but not the sensor update rate the user has to take care to set the sensor speed accordingly. See "TSD Speed Config" below. Otherwise the program could crash.

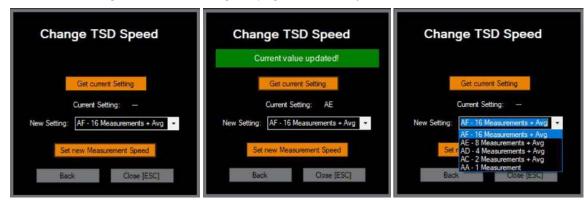
### Advanced Menu

By clicking the "Advanced" button the following menu appears:



### Change TSD Speed

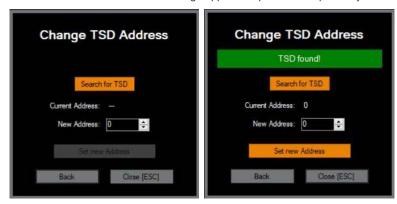
The "Change TSD Speed" menu enables the user to temporary change the oversampling rate of the sensor. As mentioned in the datasheet there are 5 different commands initiate a measurement cycle at the TSD. Per default the command "0xAF" is used where 16 measurements are taken and are internally processed to an average value. To accelerate sensor data output this oversampling rate can be modified using a different measurement command. The pictures below show the process how to change the measurement command used by the software. This will not be stored in a config file therefore the setting after program start is always "0xAF".



By clicking "Get current Setting" the current command the software uses is read. In the pull-down menu the user can now change the command to the one he would like to use. By clicking "Set new Measurement Speed" the value is taken and the software will use the new command now.

### Change TSD Address

To change the I<sup>2</sup>C address of the TSD the user must search for a TSD first by clicking "Search for TSD". Then the I<sup>2</sup>C bus is scanned for a TSD. If one is found the software shows the address at "Current address". IN the field "New address" the new address can be selected. "Set new Address" writes the value to the TSDs EEPROM. Then a message appears to perform one power cycle to make the change active.



Per default DTSViewer uses I2C address 0x00. If there is no TSD with this address a message appears if the user wants to scan the bus. By clicking "Yes" the bus is scanned and the Software uses now the I2C address of the connected sensor.

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# Sensorboard Config

This function is for internal usage only.



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### **Order Information**

Further customer specific adaptations are available on request. Please refer to the table below for part name, description and order information.

Part Number	Part Desription	Comment
G-TPMO-101	TSD305-1C55 Digital Thermopile Sensor	TO5, I <sup>2</sup> C Interface, 0°C +100°C
10205977-00	TSD305-2C55 Digital Thermopile Sensor	TO5, I <sup>2</sup> C Interface, 0°C +300°C
10207697-00	TSD305-3C55 Digital Thermopile Sensor	TO5, I <sup>2</sup> C Interface Add=0x1E, 0°C +100°C
10213286-00	TSD305-1SL10 Digital Thermopile Sensor	TO5, FOV=10°, I <sup>2</sup> C Interface, 0°C +300°C
20006766-00	TSD305-Series Evaluation Kit	Contains evaluation board, one piece G-TPMO-101 and 104 and the DTS-Viewer software on USB drive

### **EMC**

Due to the use of these modules for OEM application no CE declaration is done. Especially line coupled disturbances like surge, burst, HF etc. cannot be removed by the module due to the small board area and low-price feature. There is no protection circuit against reverse polarity or over voltage implemented. The module will be designed using capacitors for blocking and ground plane areas in order to prevent wireless coupled disturbances as good as possible.

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